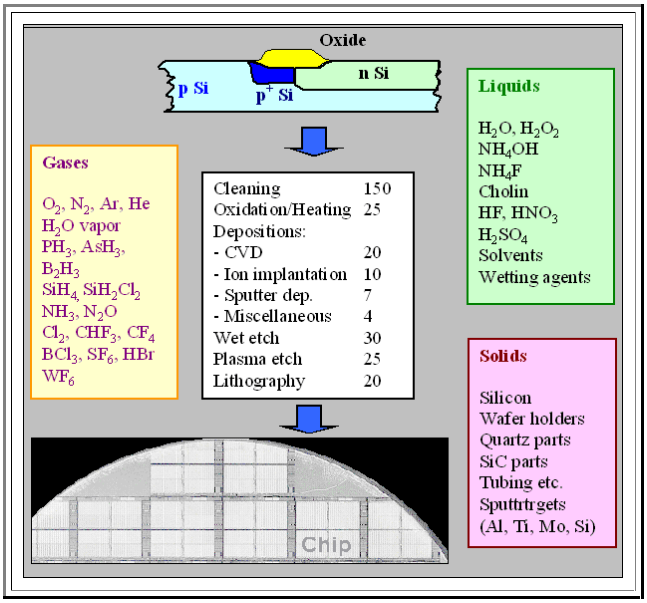
Processes and Materials II

Illustration

- Here is the rest of the processes
  - A few more materials are needed, especially solids in the form of "sputter targets".
  - A great total of about **450** process- and control steps are needed.



- We don't have a chip yet - we only have unpackaged chips on a wafer.
  - Next, the wafer has to be cut and the chips that work (this needs a measurement) are packaged.
  - Packaging, although not needing processes at very small dimensions, is not simple either.
  - **To continue, use the link**